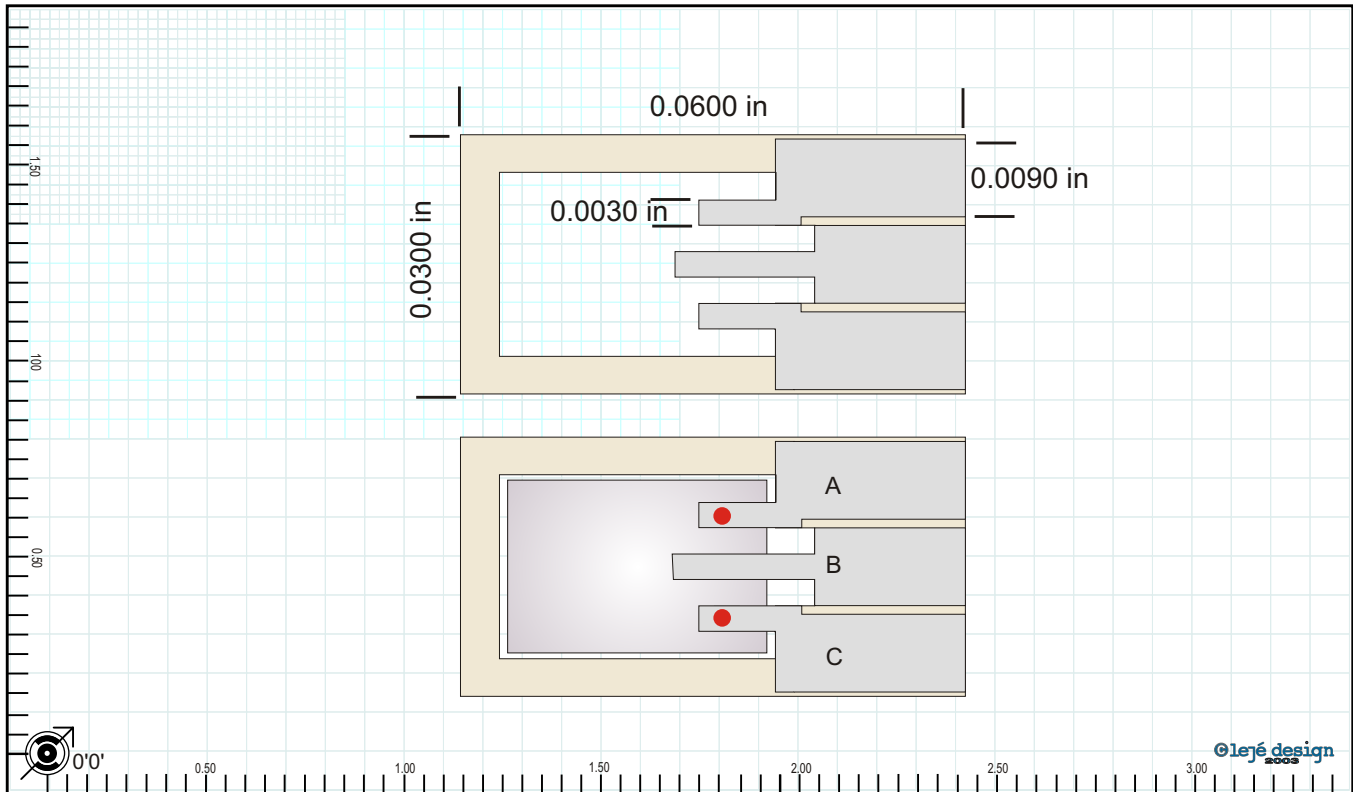


Typical three lead transistor with two bond pads top side, one bond pad bottom side. A cavity is formed from the top side exposing three leads at the bottom of the cavity

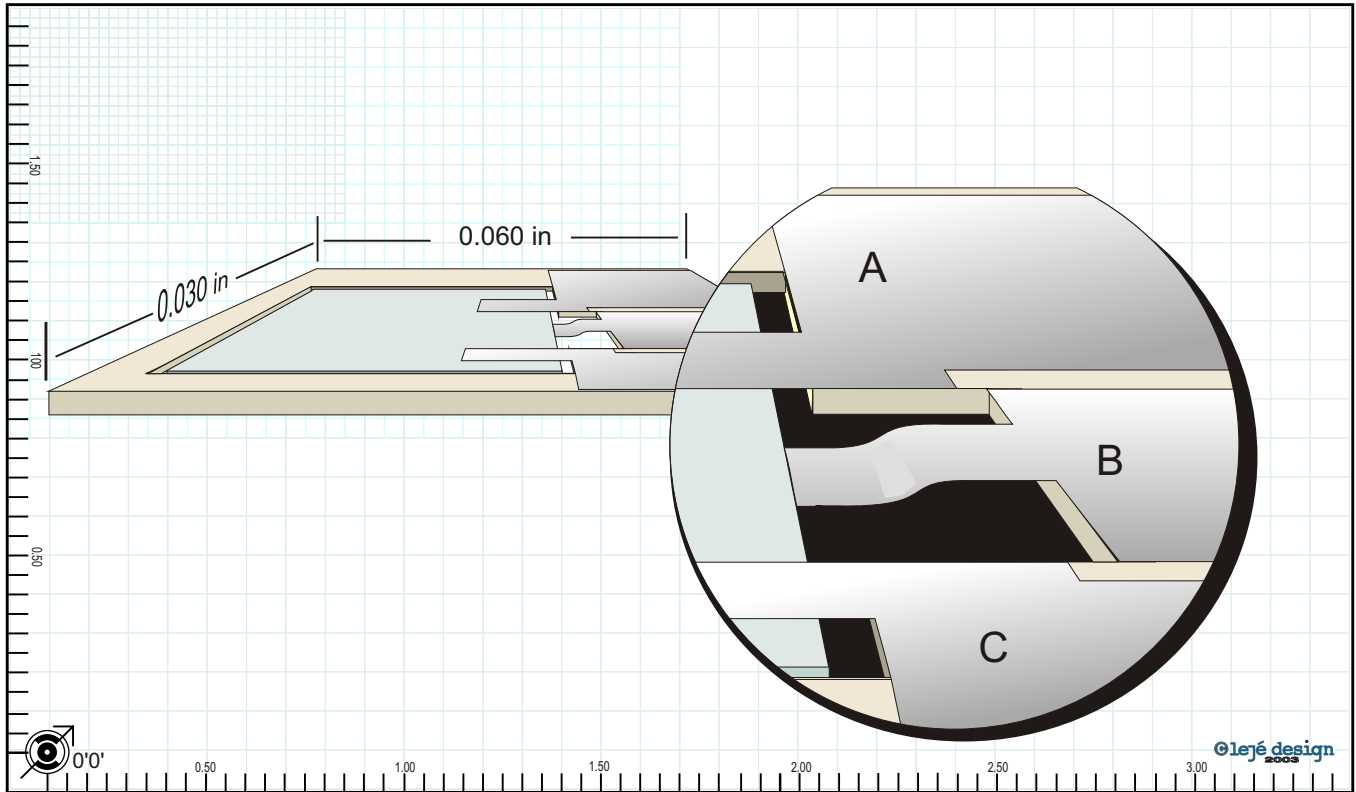


DOCUMENT NO.
D-128
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TRANSISTOR PLACEMENT

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The transistor is placed in the cavity from the top side and bond pads A and C are aligned with the leads. Leads A and C are ultrasonically bonded to the transistor pads.



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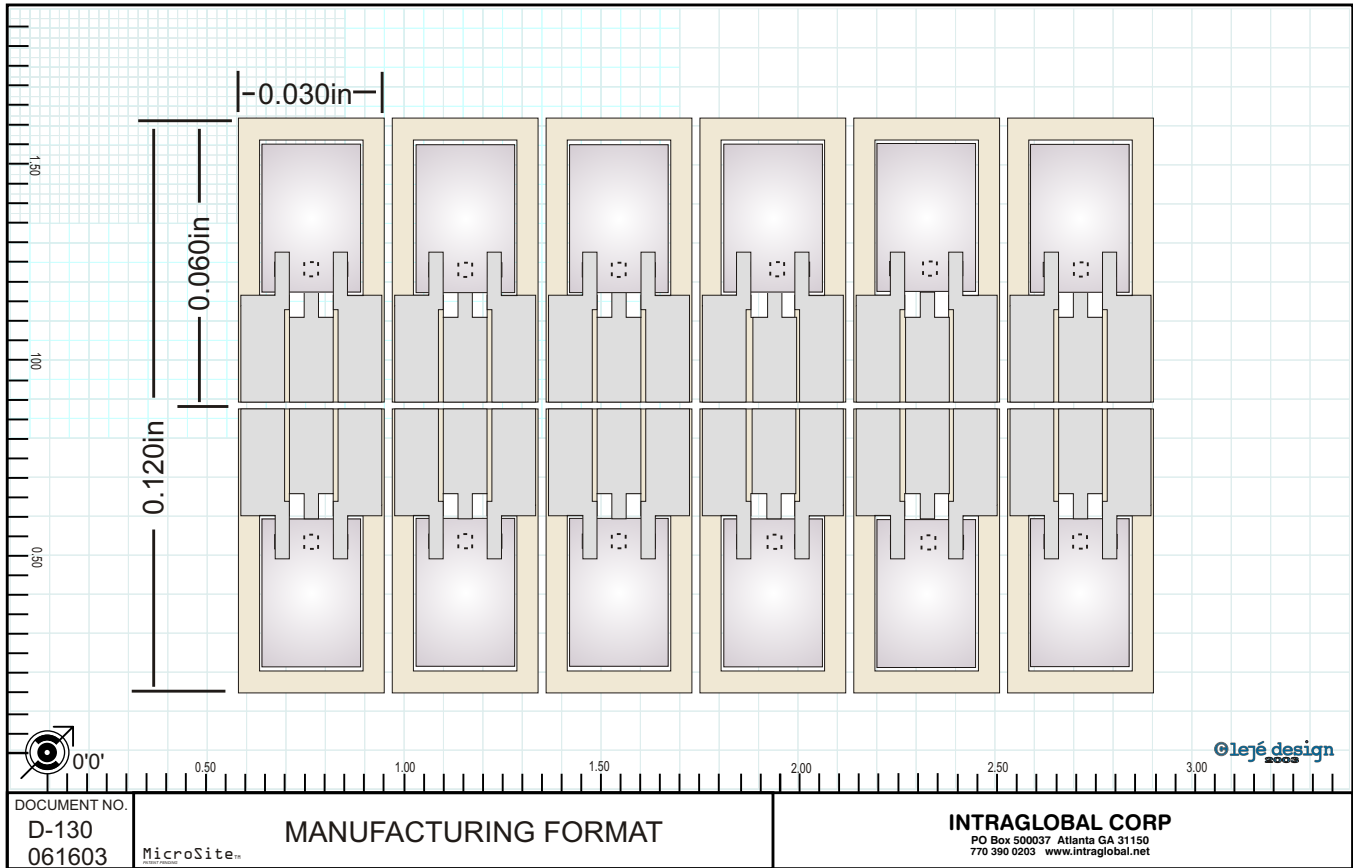
DOCUMENT NO.
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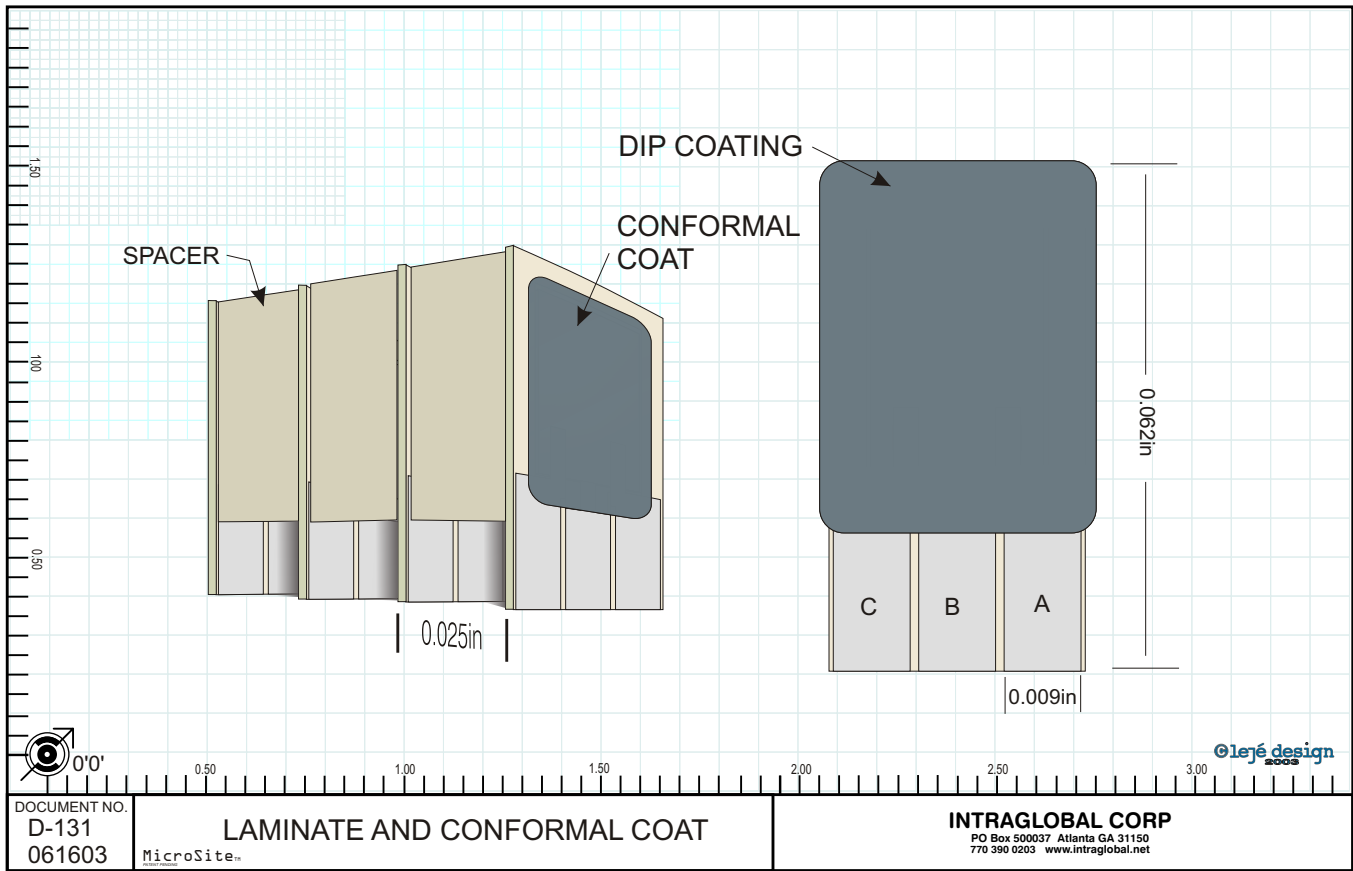
REVERSE SIDE BOND PROCEDURE

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The B' lead tab is pushed through the cavity opening and bonded to the B' bond pad on the reverse side of the transistor.



The transistor lead frame is manufactured in tape or array format for ease of handling.



The transistor package is dip coated in the strip or laminated and conformally coated.